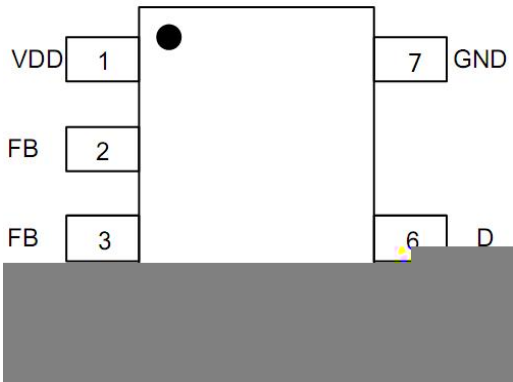
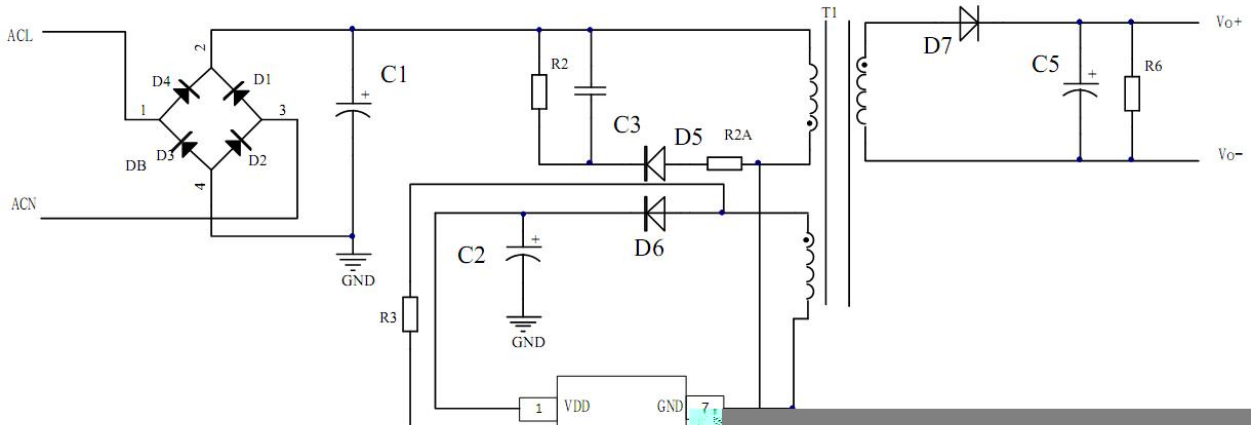




A	6/16	ALL	YC-RM3354S BRAD6315DSA		



1	VDD	
2 -3	FB	
4	CS	
5-6	D	MOS
7	GND	



D Pin Voltage Range	-0.3 to 650	V
V _{DD} DC Clamping Current	10	mA
V _{DD} DC Supply Voltage	-0.3 to 34.5	V
CS Voltage Range	-0.3 to 7	V
FB Voltage Range	-0.7 to 7	V
Package Thermal Resistance	80	°C/W
Maximum Junction Temperature	150	°C
Operating Temperature Range	0 to +125	°C
Storage Temperature Range	-65 to +150	°C
Lead Temperature (Soldering,10sec.)	260	°C
ESD Capability,HBM(Human Body Model)	3000	V
ESD Capability,MM(Machine Model)	250	V

Note 1: If the device operating conditions over the maximum rating of the above-mentioned conditions, may cause permanent damage to the device. The above parameters is only part of the operating conditions the maximum, we do not recommend the device running outside the scope of this specification. If the device to work long hours under the condition of absolute maximum limit, its stability may be affected.



Start-up current into VDD pin	I_{VDD_st}			2	25	uA
Quiescent current into VDD pin	I_Q			0.5	1	mA
Operation Current VDD Under Voltage Lock	I_{VDD_Op}	$V_{FB}=1.1V,$ $VDD=18V$ ef	0.3 C	0.7	0.9	mA





BRAD6315DSA

DCM

BRAD6315DSA

2uA

IC

16.3V

BRAD6315DSA

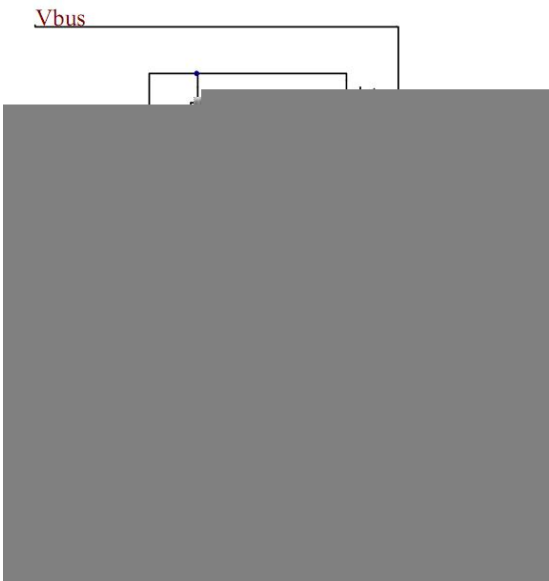
VDD

1mA

VDD

BRAD6315DSA

0.5mA



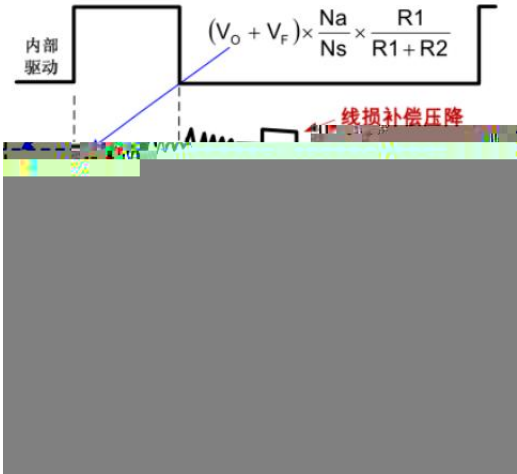
PSR-CVM

2

BRAD6315DSA
VF

CV

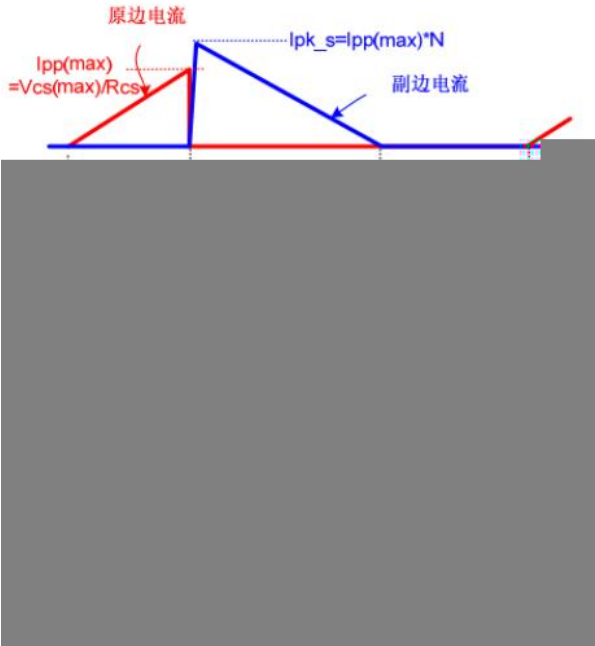
2V





	BRAD6315DSA		
FB	2	FB	2
$V_{FB} = (V_O + V_F) \times \frac{N_a}{N_s} \times \frac{R1}{R1+R2}$			
	$\frac{V_o}{N_s}$	$\frac{V_F}{N_a}$	$\frac{R1}{R2}$
FB	2V		

PSR-CCM			
FB	CS		3



3		Tdem	3
			Tsw

VDD		BRAD6315DSA
Tdem	Tsw	1/2

$$I_{CC_OUT}(mA) \cong \frac{1}{4} \times N \times \frac{500mV}{Rcs(\Omega)}$$

N----		
Rcs---	MOS	GND



4
FM

BRAD6315DSA
AM

70mW



CDC

5
BRAD6315DSA

FB

FB

R1 R2

$$\frac{\Delta V(\text{cable})}{V_{\text{out}}} \approx \frac{I_{\text{cable_max}} \times (R1//R2)}{V_{\text{FB_REF}}} \times 100\%$$

R1=3KΩ R2=18KΩ

$$\frac{\Delta V(\text{cable})}{V_{\text{out}}} = \frac{36\mu\text{A} \times (3\text{K} // 18\text{K})}{2\text{V}} \times 100\% = 4.6\%$$

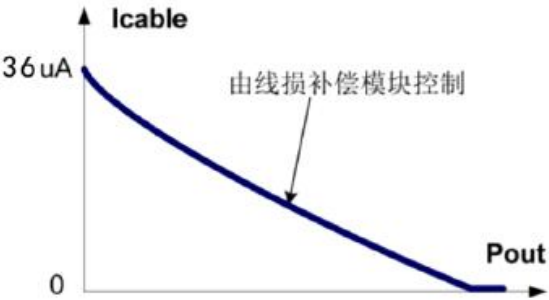
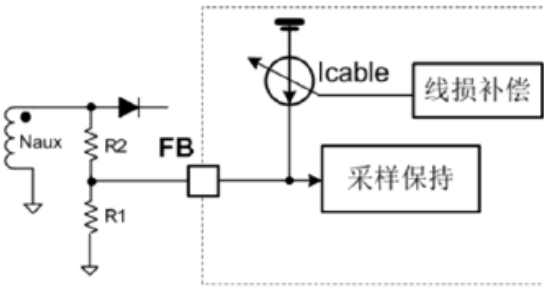
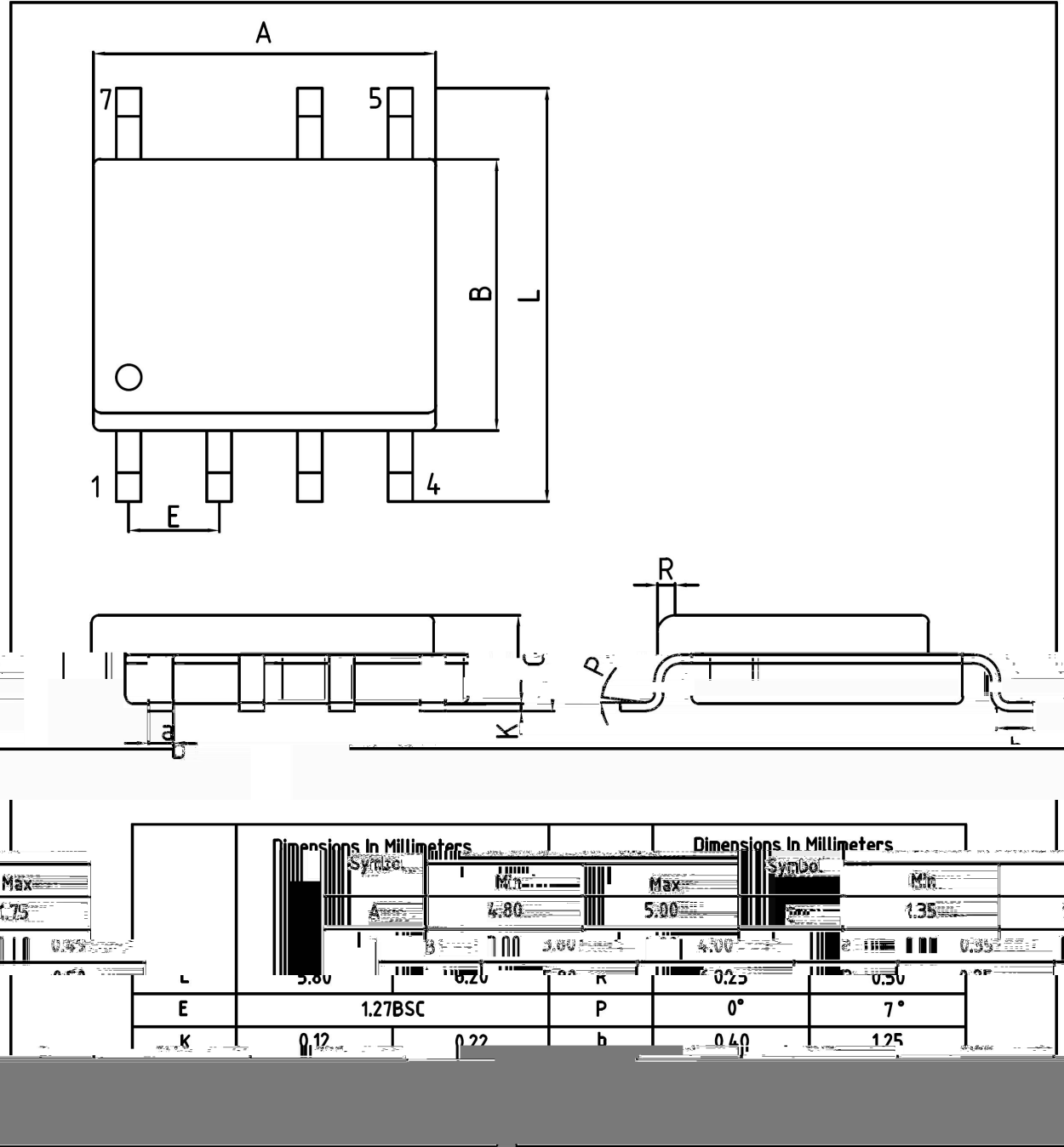


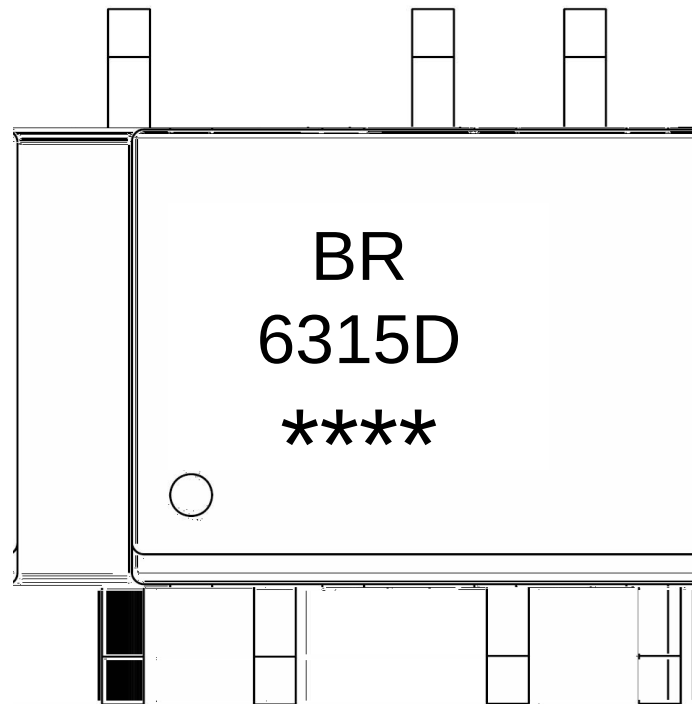
图 5



SOP-7

单位: mm





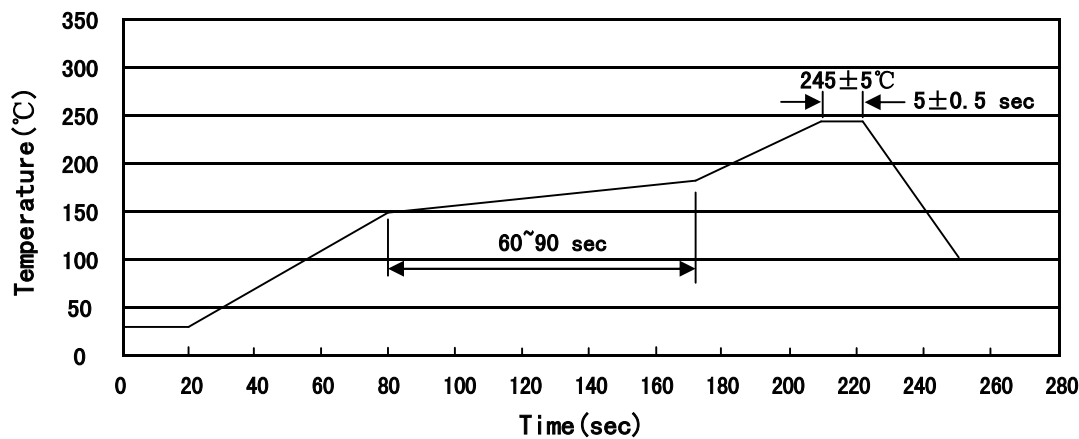
BR
6315D

Note

BR	Company Code
6315D	Product Typ
****	Lot No.Code,code change with Lot No



Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

温度：260±5°C 时间：10±1 sec. Temp.:260±5°C Time:10±1 sec

卷盘包装 / REEL

Package Type	Units					Dimension (unit mm)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box	Outer Box
SOP-7	4,000	2	8,000	6	48,000	13" ×12	360×360×50	380×335×366